# Gap Pad® A2000

High Performance, Thermally Conductive Gap Filling Material

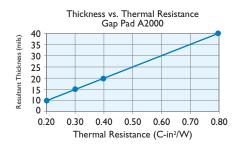
### **Features and Benefits**

- Thermal conductivity: 2.0 W/m-K
- Fiberglass reinforced for puncture, shear and tear resistance
- · Electrically isolating



Gap Pad A2000 acts as a thermal interface and electrical insulator between electronic components and heat sinks. In the thickness range of 10 to 40 mil, Gap Pad A2000 is supplied with natural tack on both sides, allowing for excellent compliance to the adjacent surfaces of components. The 40 mil material thickness is supplied with lower tack on one side, allowing for burn-in processes and easy rework.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD A2000						
PROPERTY	IMPERIAL VALUE	METRIC V	1ETRIC VALUE		TEST METHOD	
Color	Gray	Gray		Visual		
Reinforcement Carrier	Fiberglass	Fiberglass		_		
Thickness (inch) / (mm)	0.010 to 0.040	0.254 to 1.016		ASTM D374		
Inherent Surface Tack (1 side)	2	2		_		
Density (Bulk Rubber) (g/cc)	2.9	2.9		ASTM D792		
Heat Capacity (J/g-K)	1.0	1.0		ASTM E1269		
Hardness (Bulk Rubber) (Shore 00) (1)	80	80		ASTM D2240		
Young's Modulus (psi) / (kPa) (2)	55	379		ASTM D575		
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200		_		
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	>4000	>4000		ASTM D149		
Dielectric Constant (1000 Hz)	6.0	6.0		ASTM D150		
Volume Resistivity (Ohm-meter)	10"	1011		ASTM D257		
Flame Rating	V-O	V-O		U.L. 94		
THERMAL						
Thermal Conductivity (W/m-K)	2.0	2.0		ASTM D5470		
THERMAL PERFORMANCE vs. STRAIN						
	Deflection (% strain)		10	20	30	
Thermal Impedance (°C-in²/W) 0.040" (3)			1.04	1.00	0.95	
1) Thirty second delay value Shore 00 hardness scale, 2) Young's Modulus, calculated using 0.01 in/min, step rate of strain						

## **Typical Applications Include:**

surface roughness, flatness and pressure applied

- Computer and peripherals; between CPU and heat spreader
- Telecommunications
- Heat pipe assemblies
- RDRAM™ memory modules
- CDROM / DVD cooling
- Areas where heat needs to be transferred to a frame chassis or other type of heat spreader

with a sample size of 0.79 inch². 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial ther-

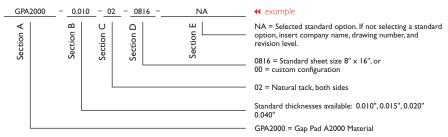
mal resistance. These values are provided for reference only. Actual application performance is directly related to the

• DDR SDRAM memory modules

## **Configurations Available:**

• Sheet form, die-cut parts and roll form (converted or unconverted)

## **Building a Part Number Standard Options**



Note: To build a part number, visit our website at www.bergquistcompany.com.



www.bergquistcompany.com

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